

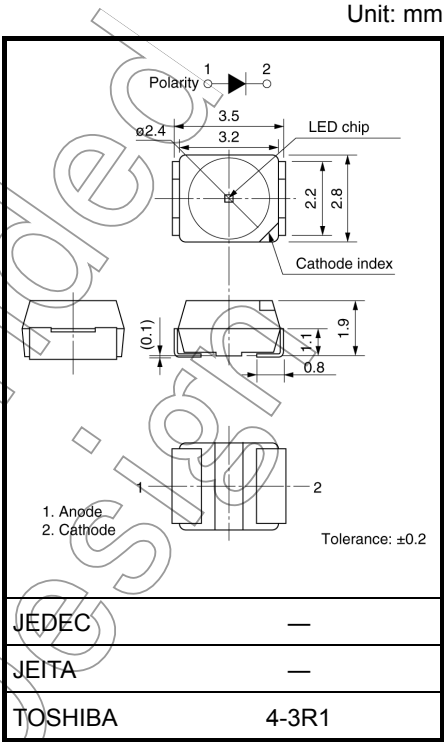
TLGH1100B(T11), TLFGH1100B(T11), TLPGH1100B(T11)

Panel Circuit Indicators

- Surface-mount devices
- 3.2 (L) mm × 2.8 (W) mm × 1.9 (H) mm
- Flat-top type
- InGaAlP LEDs
- High luminous intensity
- Low drive current, high-intensity light emission
- Colors: green, pure green
- Applications: automotive use, message signboards, backlighting etc.
- Standard embossed tape packing: T11 (2000 pcs / reel)
8-mm tape reel

Color and Material

Part Number	Color	Material
TLGH1100B	Green	InGaAlP
TLFGH1100B	Green	
TLPGH1100B	Pure Green	



Weight: 0.035 g (typ.)

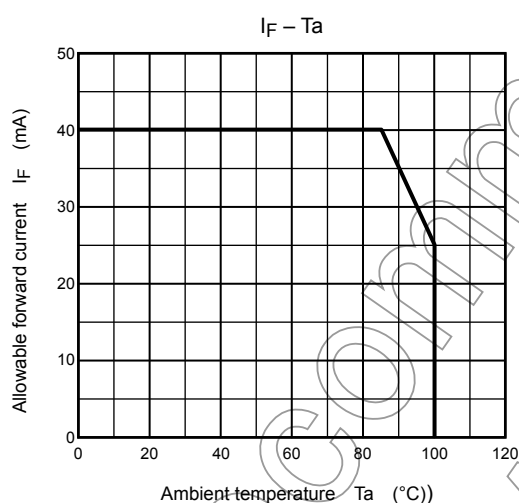
Absolute Maximum Ratings (Ta = 25°C)

Product Name	Forward Current I _F (mA) Please see Note 1	Reverse Voltage V _R (V)	Power Dissipation P _D (mW)	Operation Temperature T _{opr} (°C)	Storage Temperature T _{stg} (°C)
TLGH1100B	40	4	100	-40 to 100	-40 to 100
TLFGH1100B					
TLPGH1100B					

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Forward current derating



Electrical Characteristics (Ta = 25°C)

Product Name	Forward Voltage V _F			Reverse Current I _R	
	Min	Typ.	Max	I _F	V _R
TLGH1100B	1.8	2.1	2.5	20	10
TLFGH1100B	1.8	2.1	2.5		
TLPGH1100B	1.8	2.15	2.5		
Unit	V			mA	μA

Optical Characteristics-1 (Ta = 25°C)

Product Name	Luminous Intensity I _v				Available I _v rank Please see Note 2
	Min	Typ.	Max	I _F	
TLGH1100B	63	150	320	20	QA / RA / SA
TLFGH1100B	40	70	200	20	PA / QA / RA
TLP GH1100B	16	35	80	20	MA / NA / PA
Unit	mcd	mcd	mcd	mA	

Note 2: The specification on the above table is used for I_v classification of LEDs in Toshiba facility.
Each reel includes the same rank LEDs. Let the delivery ratio of each rank be unquestioned.

Rank	Luminous Intensity I _v	
	Min	Max
MA	16	32
NA	25	50
PA	40	80
QA	63	125
RA	100	200
SA	160	320
Unit	mcd	mcd

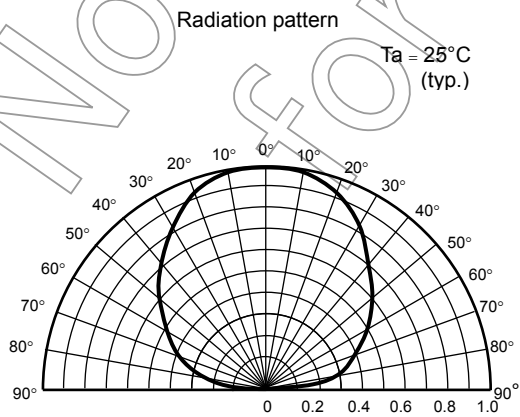
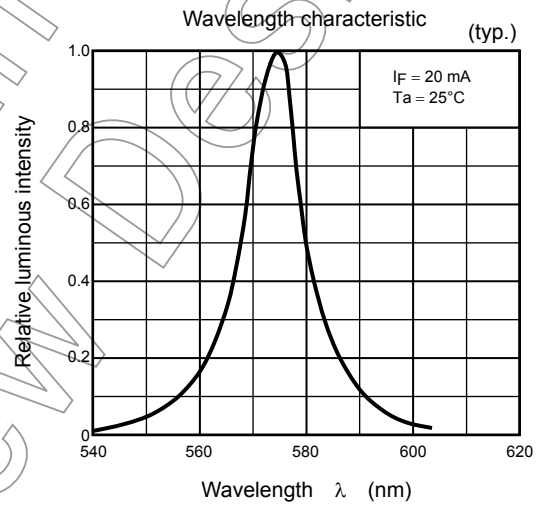
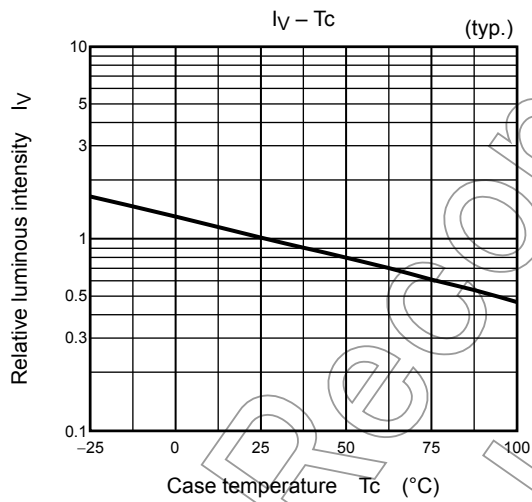
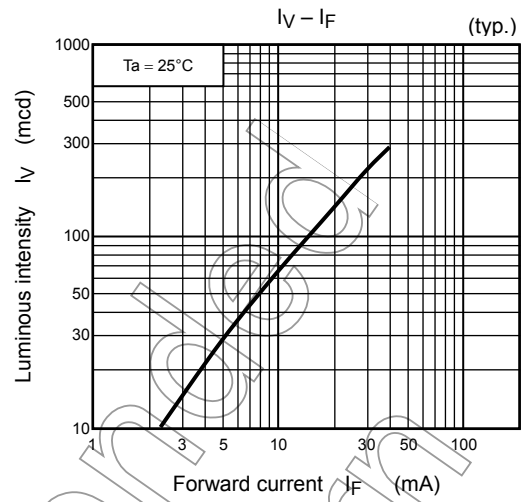
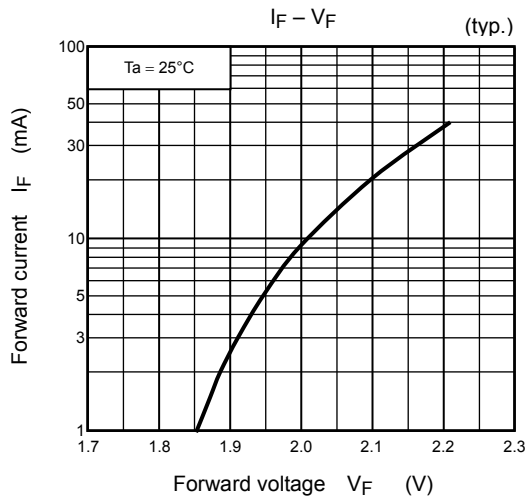
Optical Characteristics-2 (Ta = 25°C)

Product Name	Emission Spectrum							I _F
	Peak Emission Wavelength λ _p			Δλ	Dominant Wavelength λ _d			
	Min	Typ.	Max	Typ.	Min	Typ.	Max	
TLGH1100B	—	574	—	12	565	571	576	20
TLFGH1100B	—	568	—	12	561	565	569	
TLP GH1100B	—	562	—	12	555	558	564	
Unit	nm			nm	nm			mA

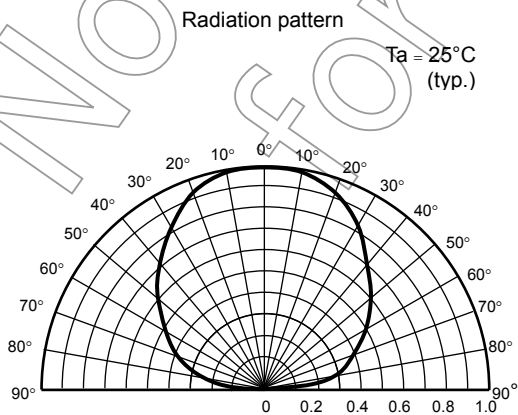
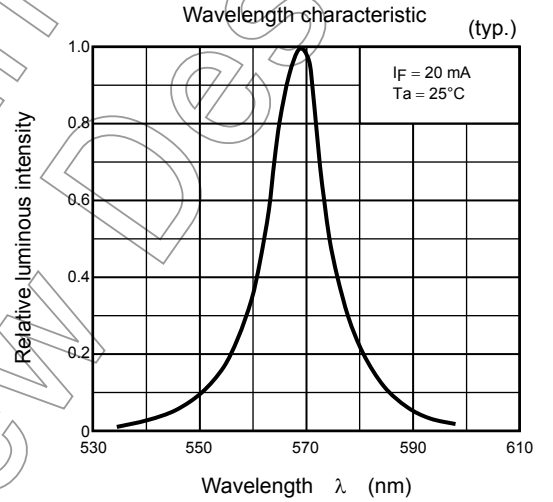
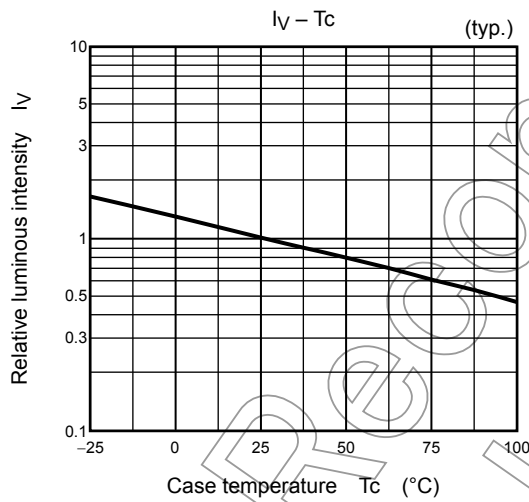
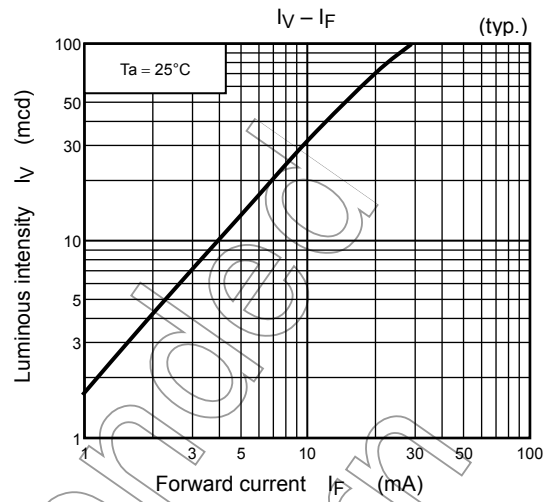
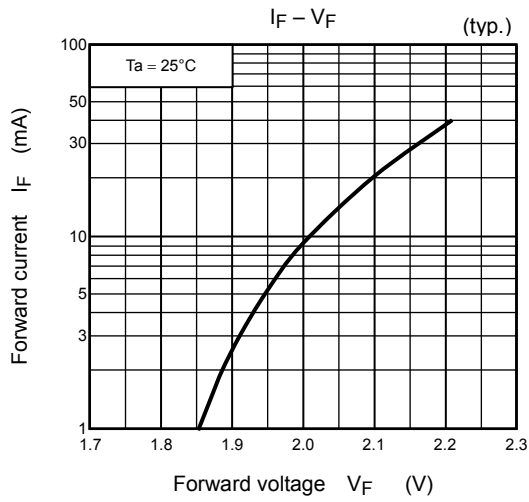
Cautions

- This visible LED lamp also emits some IR light.
If a photodetector is located near the LED lamp, please ensure that it will not be affected by the IR light.
- This product is designed as a general display light source usage, and it has applied the measurement standard that matched with the sensitivity of human's eyes. Therefore, it is not intended for usage of functional application (ex. Light source for sensor, optical communication, etc.) except general display light source.

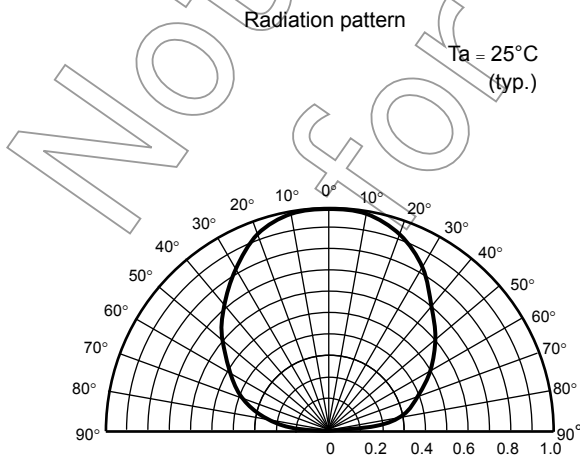
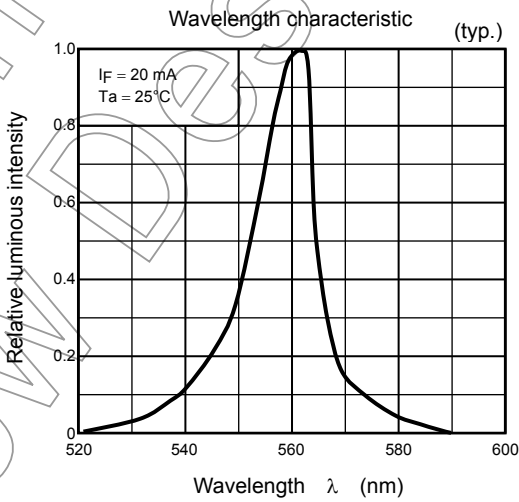
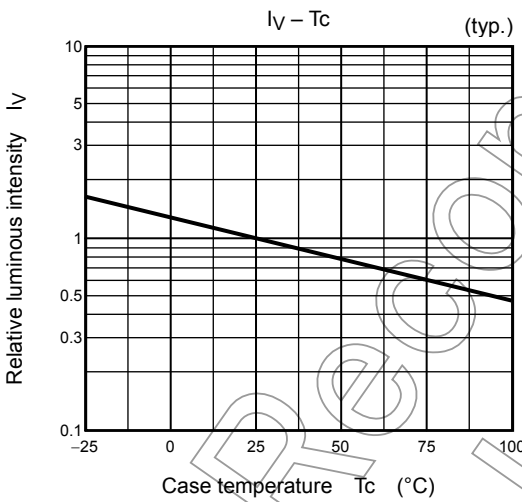
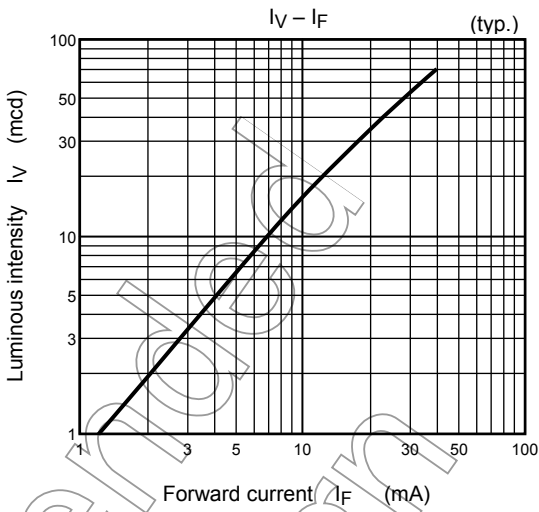
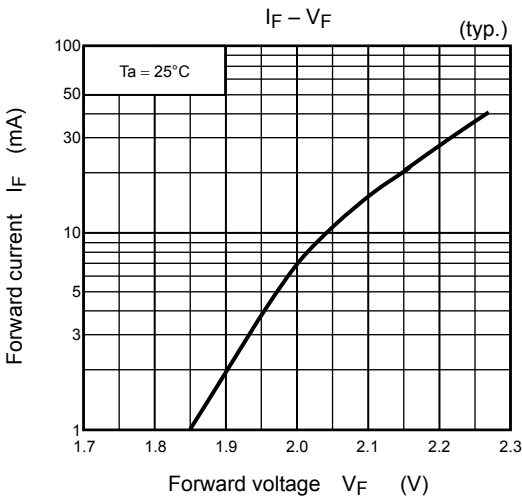
TLGH1100B



TLFGH1100B



TLPGH1100B



Packaging

These LED devices are packed in an aluminum envelope with a silica gel and a moisture indicator to avoid moisture absorption. The optical characteristics of the devices may be affected by exposure to moisture in the air before soldering and they should therefore be stored under the following conditions:

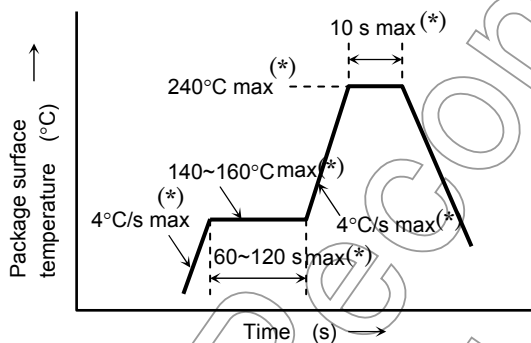
1. This moisture proof bag may be stored unopened within 12 months at the following conditions.
Temperature: 5°C to 30°C
Humidity: 90% (max)
2. After opening the moisture proof bag, the devices should be assembled within 168 hours in an environment of 5°C to 30°C/60% RH or below.
3. If upon opening, the moisture indicator card shows humidity 30% or above (Color of indication changes to pink) or the expiration date has passed, the devices should be baked in taping with reel.
After baking, use the baked devices within 72 hours, but perform baking only once.
Baking conditions: 60±5°C, for 12 to 24 hours.
Expiration date: 12 months from sealing date, which is imprinted on the same side as this label affixed.
4. Repeated baking can cause the peeling strength of the taping to change, then leads to trouble in mounting.
Furthermore, prevent the devices from being destructed against static electricity for baking of it.
5. If the packing material of laminate would be broken, the hermeticity would deteriorate. Therefore, do not throw or drop the packed devices.

Mounting Method

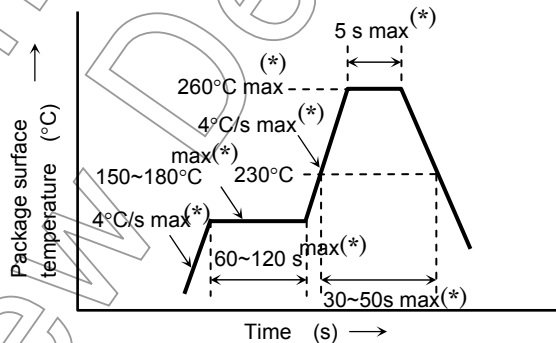
Soldering

- Reflow soldering (example)

Temperature profile for Pb soldering (example)



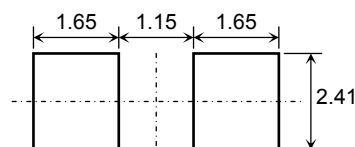
Temperature profile for Pb-free soldering (example)



- The products are evaluated using above reflow soldering conditions. No additional test is performed exceed the condition (i.e. the condition more than (*)MAX values) as a evaluation. Please perform reflow soldering under the above conditions.
- Please perform the first reflow soldering with reference to the above temperature profile and within 168 h of opening the package.
- Second reflow soldering
In case of second reflow soldering should be performed within 168 h of the first reflow under the above conditions.
Storage conditions before the second reflow soldering: 30°C, 60% RH (max)
- Make any necessary soldering corrections manually.
(only once at each soldering point)
Soldering iron: 25 W
Temperature : 300°C or less
Time: within 3 s
- If the products need to be performed by other soldering method (ex. wave soldering), please contact Toshiba sales representative.

Recommended soldering pattern

Unit: mm



Cleaning

When cleaning is required after soldering, Toshiba recommends the following cleaning solvents.
It is confirmed that these solvents have no effect on semiconductor devices in our dipping test (under the recommended conditions). In selecting the one for your actual usage, please perform sufficient review on washing condition, using condition and etc.

ASAHI CLEAN AK-225AES:

(made by ASAHI GLASS)

KAO CLEAN THROUGH 750H:

(made by KAO)

PINE ALPHA ST-100S:

(made by ARAKAWA CHEMICAL)

Precautions when Mounting

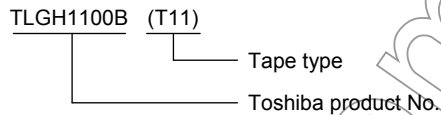
Do not apply force to the plastic part of the LED under high-temperature conditions.
To avoid damaging the LED plastic, do not apply friction using a hard material.
When installing the PCB in a product, ensure that the device does not come into contact with other components.

Tape Specifications

1. Product number format

The type of package used for shipment is denoted by a symbol suffix after the product number. The method of classification is as below. (this method, however does not apply to products whose electrical characteristics differ from standard Toshiba specifications)

- (1) Tape Type: T11 (4-mm pitch)
- (2) Example

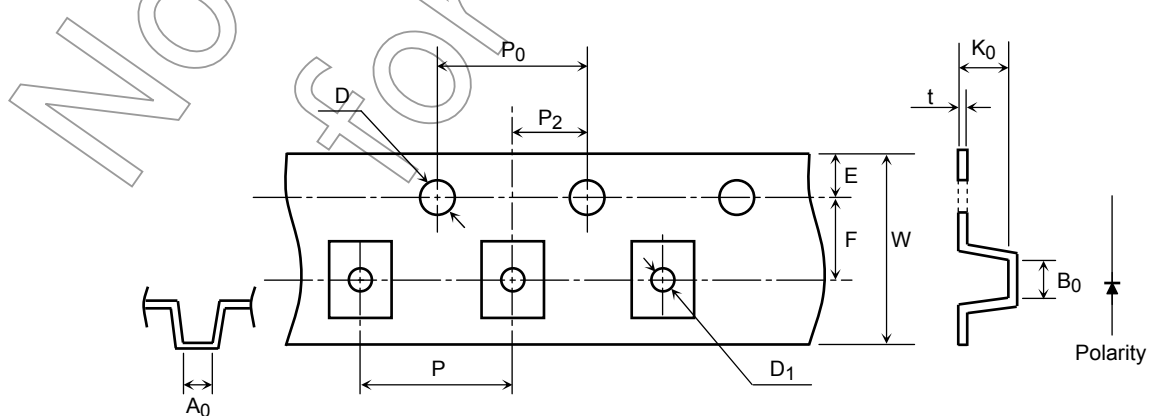


2. Tape dimensions

Unit: mm

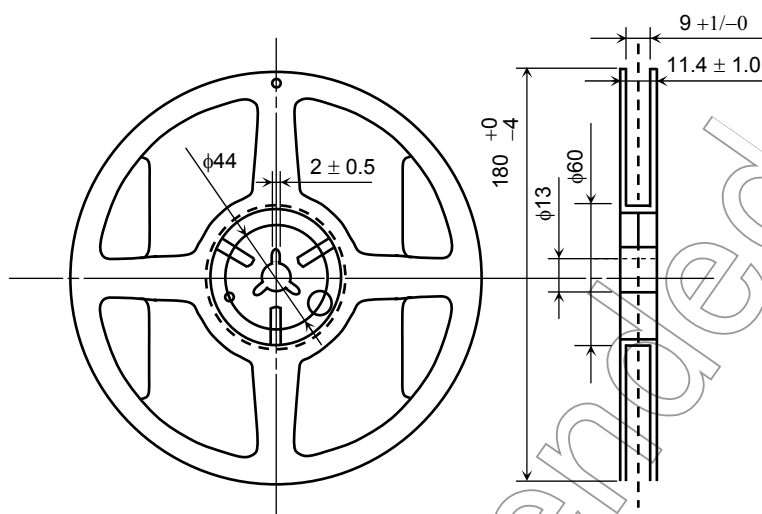
Symbol	Dimension	Tolerance
D	1.5	+0.1/-0
E	1.75	±0.1
P ₀	4.0	±0.1
t	0.3	±0.05
F	3.5	±0.05
D ₁	1.5	±0.1

Symbol	Dimension	Tolerance
P ₂	2.0	±0.05
W	8.0	±0.3
P	4.0	±0.1
A ₀	2.9	±0.1
B ₀	3.7	±0.1
K ₀	2.3	±0.1

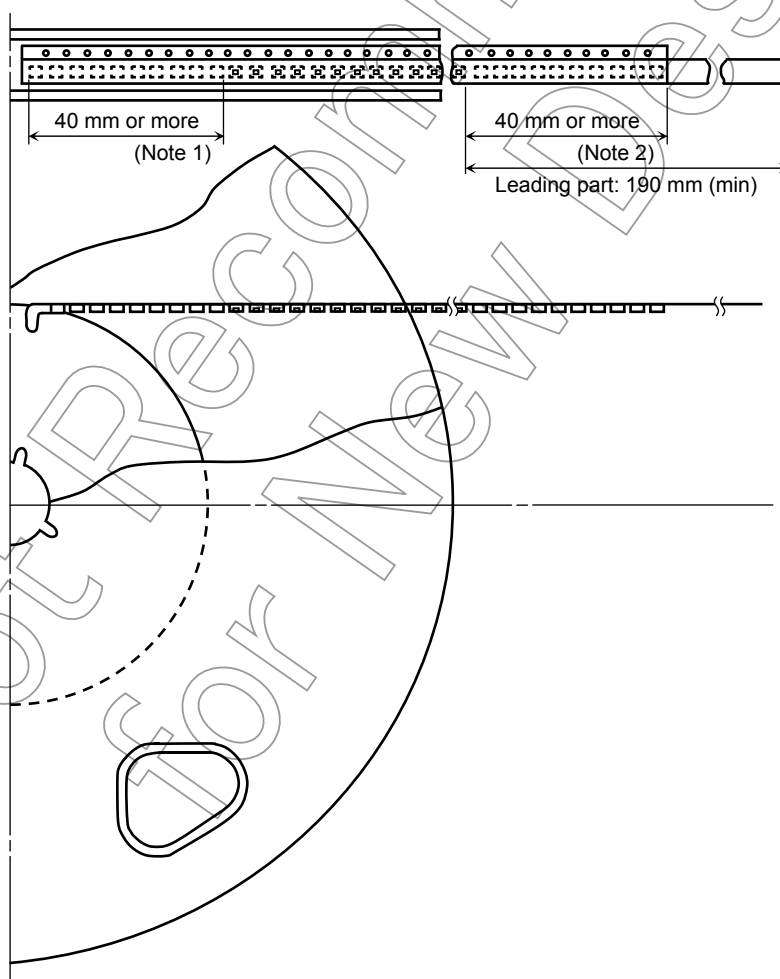


3. Reel dimensions

Unit: mm



4. Leader and trailer sections of tape



Note1: Empty trailer section

Note2: Empty leader section

5. Packing form

(1) Packing quantity

Reel	2,000 pcs
Carton	10,000 pcs

(2) Packing form: Each reel is sealed in an aluminum pack with silica gel.

6. Label format

(1) Example: TLGH1100B (T11)

P/N:

TYPE	TLGH1100B		
ADDC	(T11)	Q'TY	2,000 pcs

Lot Number

Key code for TSB

(RANK SYMBOL)

32C

2000

Use under 5-30degC/60%RH within 168h

[[G]]/RoHS COMPATIBLE

Y380xxxxxxxxxxxxxxxx

SEALING

DIFFUSED IN *****

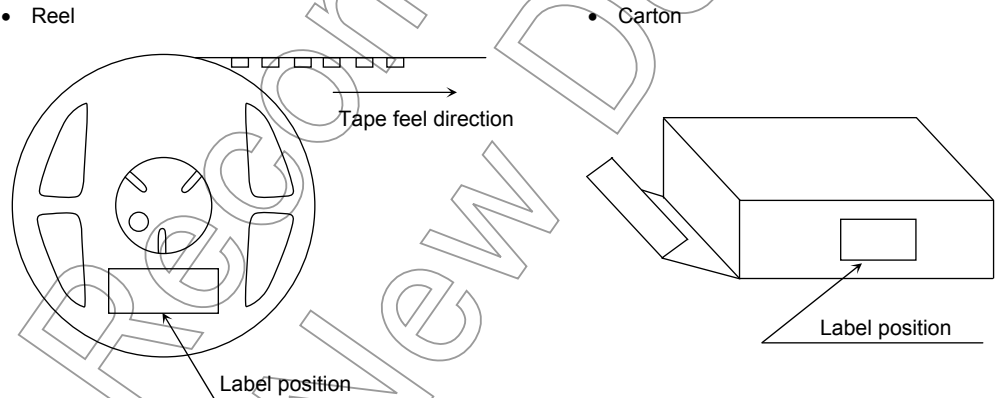
ASSEMBLED IN *****

TOSHIBA





(2) Label location



• The aluminum package in which the reel is supplied also has the label attached to center of one side.

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